



Material Content Data Sheet



Halogen-Free

Sales Product Name	BFP 843F H6327	Issued	15. April 2021
MA#	MA001351580		
Package	PG-TSFP-4-1	Weight*	1.87 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.04		376	
	noble metal	gold	7440-57-5	0.003	0.15		1457	
	inorganic material	silicon	7440-21-3	0.024	1.28	1.47	12831	14664
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		394	
	non noble metal	chromium	7440-47-3	0.002	0.12		1183	
	non noble metal	copper	7440-50-8	0.734	39.26	39.43	392592	394248
wire	noble metal	gold	7440-57-5	0.007	0.35	0.35	3515	3515
encapsulation	organic material	carbon black	1333-86-4	0.010	0.51		5133	
	plastics	epoxy resin	-	0.206	11.04		110352	
	inorganic material	silicondioxide	60676-86-0	0.744	39.77	51.32	397779	513264
leadfinish	non noble metal	tin	7440-31-5	0.049	2.62	2.62	26171	26171
plating	noble metal	silver	7440-22-4	0.090	4.81	4.81	48138	48138
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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